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(54) **SYSTEM AND METHOD FOR THERMAL MANAGEMENT USING LIQUID COOLING**

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(57) **ABSTRACT**

An information handling system includes a computing device, the information handling system includes a computing component of the computing device that is housed in a chassis; and a heating component that increases a temperature of a portion of an airflow when the heating component is in an active state, the portion of the airflow thermally manages the computing component by reducing a temperature of the computing component. The airflow is received by the chassis via an air receiving exchange, and exhausted by the chassis via an air expelling exchange.

